



Full Material Declaration for attached parts list

Report generated: 21 February 2025, 11:03 GMT



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Declarations authorised by
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Declaration effective from: 30 December 2013 [Approved: 21 February 2025 11:02 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	3.81%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.5%
			ALUMINUM, ELEMENTAL	7429-90-5	1%
			GOLD, ELEMENTAL	7440-57-5	1%
			Silicon	7440-21-3	97.5%
			Carbon black	1333-86-4	1%
Encapsulation	EP (Epoxy resin)	56.75%	Phenol, polymer with formaldehyde	9003-35-4	7%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	8%
			Silicone dioxide	60676-86-0	84%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	1.38%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.38%	Tin	7440-31-5	100%
			MANGANESE, ELEMENTAL	7439-96-5	0.8%
Leadframe	Nickel and Nickel alloys	36.68%	Elemental nickel REACH Article 67 Exemption	7440-02-0	42.5%
			Elemental iron	7439-89-6	56.7%

Attached parts list

Part number	Part name
SOD-523 (JA) Pb&H-Free	Diode SMD